

#### **Overview**

The PHE845 series is constructed of metallized polypropylene film encapsulated with self-extinguishing resin in a box of material that meets the requirements of UL 94 V-0.

#### **Benefits**

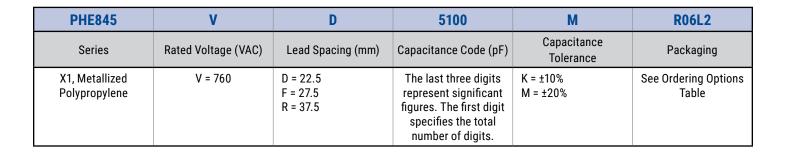
- Approvals: ENEC, UL, cUL
- Class X1 (IEC 60384-14)
- Rated voltage: 760 VAC 50/60 Hz
- Capacitance range: 0.01 1.0 μF
- Lead spacing: 22.5 37.5 mm
- Capacitance tolerance: ±20%, ±10%
- Climatic category 40/105/56/B, IEC 60068-1
- Tape & Reel in accordance with IEC 60286-2
- · RoHS compliant and lead-free terminations
- Operating temperature range of -40°C to +105°C
- 100% screening factory test at 4,250 VDC
- Self-healing properties

**Customer Part Number** 

## 3-1 -2 s

**Applications** 

danger of electric shock.

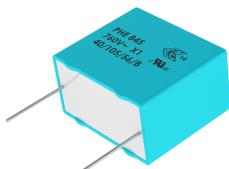


#### **KEMET Internal Part Number**

F	845	D	D	103	Μ	760	С
Capacitor Class	Series	Lead Spacing (mm)	Size Code	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VAC)	Packaging
F = Film	X1, Metallized Polypropylene	D = 22.5 F = 27.5 R = 37.5	See Dimension Table	First two digits represent significant figures. Third digit specifies number of zeros.	K = ±10% M = ±20%	760 = 760	See Ordering Options Table

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For use as an electromagnetic interference (EMI)

require X1 safety classification. Suitable for use in

suppression filter in across-the-line applications that

situations in which capacitor failure does not pose a



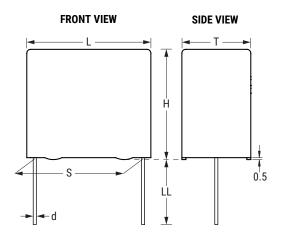
### **Ordering Options Table**

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Lead and Packaging Code	Legacy Lead and Packaging Code
	Standard Lead and Packaging Options			
	Bulk (Tray)-Short Leads	6 +0/-1	С	R06L2 <sup>(1)</sup>
	Other Lead and Packaging Options			
22.5	Pizza Pack	6 +0/-1	Z	R06L2 <sup>(1)</sup>
	Bulk (Tray)-Long Leads	30 +0/-1	ALW0L	R30L2
	Tape & Reel (Standard Reel)	H <sub>0</sub> = 18.5 ±0.5	L	R17T0
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 ±0.5	Р	R17T1
	Standard Lead and Packaging Options			
	Bulk (Tray)–Short Leads	6 +0/-1	С	R06L2 <sup>(1)</sup>
27.5	Other Lead and Packaging Options			
	Pizza Pack	6 +0/-1	Z	R06L2 <sup>(1)</sup>
	Bulk (Tray)-Long Leads	30 +0/-1	ALWOL	R30L2
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 ±0.5	Р	R17T1
	Standard Lead and Packaging			
	Options			
37.5	Bulk (Tray)–Short Leads	6 +0/-1	С	R06L2 <sup>(1)</sup>
	Other Lead and Packaging Options			
	Pizza Pack	6 +0/-1	Z	R06L2 <sup>(1)</sup>

(1) Please specify Bulk (Tray) or Pizza Packaging



#### **Dimensions – Millimeters**



<b>KEMET</b> Size	Legacy Size		S		Г	I	н		L	(	d
Code	Code	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
DD	D13	22.5	±0.4	6.5	Maximum	14.5	Maximum	26.0	Maximum	0.8	±0.05
DG	D17	22.5	±0.4	7.0	Maximum	16.5	Maximum	26.0	Maximum	0.8	±0.05
DM	D15	22.5	±0.4	9.0	Maximum	18.5	Maximum	26.0	Maximum	0.8	±0.05
DR	D18	22.5	±0.4	10.5	Maximum	19.0	Maximum	26.0	Maximum	0.8	±0.05
DT	D16	22.5	±0.4	11.0	Maximum	21.5	Maximum	26.0	Maximum	0.8	±0.05
DW	D20	22.5	±0.4	13.5	Maximum	23.0	Maximum	26.0	Maximum	0.8	±0.05
DY	D19	22.5	±0.4	15.5	Maximum	24.5	Maximum	26.0	Maximum	0.8	±0.05
FE	F11	27.5	±0.4	10.5	Maximum	20.5	Maximum	31.5	Maximum	0.8	±0.05
FG	F12	27.5	±0.4	11.5	Maximum	22.5	Maximum	31.5	Maximum	0.8	±0.05
FK	F03	27.5	±0.4	13.5	Maximum	23.0	Maximum	31.5	Maximum	0.8	±0.05
FS	F15	27.5	±0.4	19.0	Maximum	29.0	Maximum	31.5	Maximum	0.8	±0.05
FV	F16	27.5	±0.4	21.0	Maximum	30.0	Maximum	31.5	Maximum	0.8	±0.05
RH	R04	37.5	±0.5	15.0	Maximum	26.0	Maximum	41.0	Maximum	1.0	±0.05
RK	R02	37.5	± 0.5	16.5	Maximum	32.0	Maximum	41.0	Maximum	1.0	±0.05
RM	R03	37.5	±0.5	19.0	Maximum	36.0	Maximum	41.0	Maximum	1.0	±0.05
RP	R06	37.5	±0.5	21.0	Maximum	38.0	Maximum	41.0	Maximum	1.0	±0.05
		Note:	See the Orde	ering Optior	is Table for l	ead length (	LL) options.				



#### **Performance Characteristics**

Dielectric	Polypropylene film						
Plates	Metal layer deposited by evaporation under vacuum						
Winding	Non-inductive type. Triple des	sign.					
Leads	Tinned wire						
Protection	Plastic case, thermosetting res	n-filled. Box material is solver	nt-resistant and flame-retarda	ant according to UL94 V–0.			
Rated Voltage (V <sub>R</sub> )	760 VAC 50/60 Hz						
Capacitance Range	0.010 – 1.0 µF						
Capacitance Values	E6 series (IEC 60063)						
Capacitance Tolerance	±20% standard, ±10% option						
Temperature Range	-40°C to 105°C						
Climatic Category	40/105/56/B IEC 60068-1						
Approvals	ENEC, UL, cUL						
Related Documents	EN/IEC 60384-14:2005, UL 60384-14, CAN/CSA E60384-14:09						
	Maximum Values at +23°C						
	Frequency	C ≤ 0.1 µF	0.1 µF < C ≤ 1 µF				
Dissipation Factor (tanδ)	1 kHz	0.1%	0.1%				
	10 kHz	0.2%	0.4%				
	100 kHz	0.6%	-				
Test Voltage Between Terminals	The 100% screening factory ter requirements in applicable equ permitted to repeat this test as failures.	ipment standards. All electri	cal characteristics are check	ked after the test. It is not			
Resonance Frequency	Tabulated self-resonance free	quencies f <sub>o</sub> (see Table 1 – R	atings & Part Number Refe	rence)			
		Measured at +25°C ±5°C, ac	cording to IEC 60384-2				
Insulation Resistance		Minimum Values Bet	ween Terminals				
	C ≤ 0.33	μF	C > 0.	.33 µF			
	≥ 30,000	ΜΩ	≥ 10,000	MΩ•μF			
In DC Applications	Recommended voltage ≤ 1,50	0 VDC					



#### **Environmental Test Data**

Test	IEC Publication	Procedure
Endurance	IEC 60384-14:2005	1.25 x V <sub>R</sub> VAC 50 Hz, once every hour increase to 1,000 VAC for 0.1 second, 1,000 hours at upper rated temperature
Vibration	IEC 60068-2-6 Test Fc	3 directions at 2 hours each 10 – 55 Hz at 0.75 mm or 98 m/s² No visible damage. No open or short circuit.
Bump	IEC 60068-2-29 Test Eb	1,000 bumps at 390 m/s <sup>2</sup> No visible damage. No open or short circuit.
Change of Temperature	IEC 60068-2-14 Test Na	Upper and lower rated temperature 5 cycles No visible damage.
Active Flammability	IEC 60384-14:2005	$V_{R}$ + 20 surge pulses at 4 kV (pulse every 5 seconds)
Passive Flammability	IEC 60384-14:2005	IEC 60384-1, IEC 60695-11-5 Needle Flame Test
Damp Heat Steady State	IEC 60068-2-78 Test Cab	+40°C and 90 – 95% RH, 56 days

### **Approvals**

Certification Body	Mark	Specification	File Number
Intertek Semko AB		EN/IEC 60384-14	SE/0140-17E
UL	c <b>FL</b> us	UL 60384 and CAN/CSA E60384-14:09 (760 VAC)	E73869

#### **Environmental Compliance**

All KEMET EMI capacitors are RoHS compliant.





#### Table 1 – Ratings & Part Number Reference

Capacitance Value (µF)	(New/ Dimensio		t beal		dV/dt (V/	New KEMET Part Number	Legacy Part Number		
	Legacy)	B	H	L L	opaonig (p)	()	µs)		
0.010	DD/D13	6.5	14.5	26.0	22.5	11	100	F845DD103(1)760(2)	PHE845VD5100(1)(2)
0.015	DD/D13	6.5	14.5	26.0	22.5	9.2	100	F845DD153(1)760(2)	PHE845VD5150(1)(2)
0.022	DD/D13	6.5	14.5	26.0	22.5	7.6	100	F845DD223(1)760(2)	PHE845VD5220(1)(2)
0.033	DF/D17	7.0	16.5	26.0	22.5	6.4	100	F845DF333(1)760(2)	PHE845VD5330(1)(2)
0.047	DM/D15	9.0	18.5	26.0	22.5	5.3	100	F845DM473(1)760(2)	PHE845VD5470(1)(2)
0.068	DR/D18	10.5	19.0	26.0	22.5	4.4	100	F845DR683(1)760(2)	PHE845VD5680(1)(2)
0.10	DT/D16	11.0	21.5	26.0	22.5	3.5	100	F845DT104(1)760(2)	PHE845VD6100(1)(2)
0.15	DW/D20	13.5	23.0	26.0	22.5	3.1	100	F845DW154(1)760(2)	PHE845VD6150(1)(2)
0.22	DY/D19	15.5	24.5	26.0	22.5	2.7	100	F845DY224M760(2)	PHE845VY6220M(2)
0.10	FE/F11	10.5	20.5	31.5	27.5	3.4	100	F845FE104(1)760(2)	PHE845VF6100(1)(2)
0.15	FG/F12	11.5	22.5	31.5	27.5	3.0	100	F845FG154(1)760(2)	PHE845VF6150(1)(2)
0.22	FK/F03	13.5	23.0	31.5	27.5	2.4	100	F845FK224(1)760(2)	PHE845VF6220(1)(2)
0.33	FS/F15	19.0	29.0	31.5	27.5	2.0	100	F845FS334(1)760(2)	PHE845VF6330(1)(2)
0.47	FV/F16	21.0	30.0	31.5	27.5	1.6	100	F845FV474M760(2)	PHE845VZ6470M(2)
0.47	RH/R04	15.0	26.0	41.0	37.5	1.6	100	F845RH474M760(2)	PHE845VW6470M(2)
0.47	RK/R02	16.5	32.0	41.0	37.5	1.6	100	F845RK474(1)760(2)	PHE845VR6470(1)(2)
0.68	RM/R03	19.0	36.0	41.0	37.5	1.2	100	F845RM684(1)760(2)	PHE845VR6680(1)(2)
1.0	RP/R06	21.0	38.0	41.0	37.5	1.0	100	F845RP105M760(2)	PHE845VW7100M(2)
Capacitance Value (µF)	Size Code (New/ Legacy)	B (mm)	H (mm)	L (mm)	Lead Spacing (p)	f <sub>。</sub> (MHz)	dV/dt (V/µs)	New KEMET Part Number	Legacy Part Number

(1)  $M = \pm 20\%$ ,  $K = \pm 10\%$ .

(2) Insert ordering code for lead type and packaging. See Ordering Options Table for available options.



#### **Soldering Process**

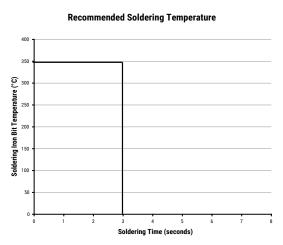
The implementation of the RoHS directive has resulted in the selection of SnAuCu (SAC) alloys or SnCu alloys as primary solder. This implementation has increased the liquidus temperature from  $183^{\circ}$ C for SnPb eutectic alloys to  $217 - 221^{\circ}$ C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher pre-heat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is  $160 - 170^{\circ}$ C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 - 15 mm), and great care must be taken during soldering. The recommended solder profiles from KEMET should be used. Consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid guideline for successful soldering. See Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the recommended limits may result in degradation of or permanent damage to the capacitors.

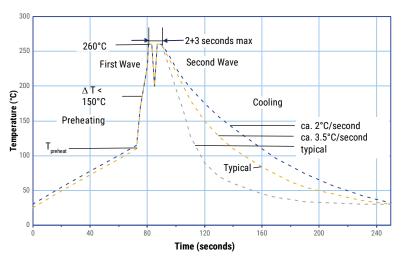
Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface-mount components. Insert through-hole parts after curing the surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum of two soldering cycles is recommended. Allow time for the capacitor surface temperature to return to normal before the second soldering cycle.

#### **Manual Soldering Recommendations**

Following is the recommendation for manual soldering with a soldering iron.



Wave Soldering Recommendations



Soldering iron tip temperature should be set at 350°C (+10°C maximum), with the soldering duration not to exceed 3 seconds.



#### **Soldering Process cont.**

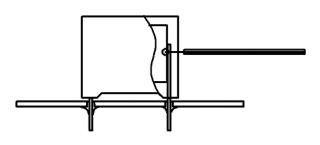
#### Wave Soldering Recommendations cont.

1. The table indicates the maximum set-up temperature of the soldering process. Figure 1

Dielectric film		n Preheat erature	Maximum Peak Solderin Temperature		
material	Capacitor Pitch ≥ 10 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	270°C	270°C	
Polypropylene	110°C	130°C	260°C	270°C	
Paper	130°C	140°C	270°C	270°C	
Polyphenylene Sulphide	150°C	160°C	270°C	270°C	

2. The maximum temperature measured inside the capacitor: set the temperature so that the maximum temperature is below the limit inside the element.

Dielectric Film Material	Maximum Temperature Measured Inside the Element
Polyester	160°C
Polypropylene	110°C
Paper	160°C
Polyphenylene Sulphide	160°C



Temperature monitored inside the capacitor.

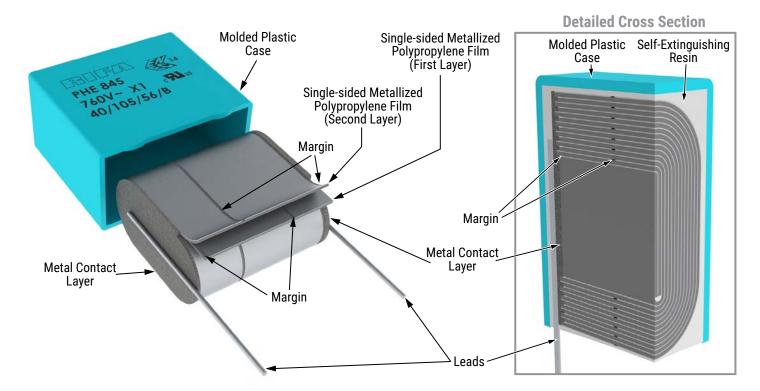
#### **Selective Soldering Recommendations**

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath, as in normal flow soldering, without touching the solder. When the board is over the bath, it is stopped. Pre-designed solder pots are lifted from the bath with molten solder only at the places of the selected components, and then pressed against the lower surface of the board to solder the components.

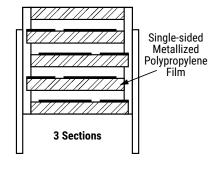
The temperature profile for selective soldering is similar to the double-wave flow soldering outlined in this document. **However, instead of two baths, there is only one with a time from 3 to 10 seconds.** In selective soldering, the risk of overheating is greater than in double-wave flow soldering. Great care must be taken so that the parts do not overheat.



#### Construction

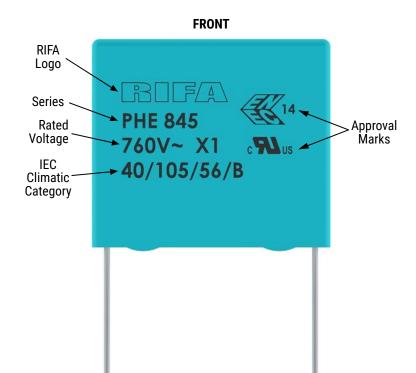


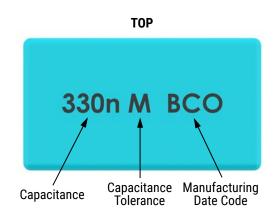
**Winding Scheme** 





#### Marking





Manufacturing Date Code (IEC-60062)											
	Y = Year, Z = Month										
Year	Code	Month	Code								
2010	А	January	1								
2011	В	February	2								
2012	С	March	3								
2013	D	April	4								
2014	E	Мау	5								
2015	F	June	6								
2016	Н	July	7								
2017	J	August	8								
2018	К	September	9								
2019	L	October	0								
2020	М	November	Ν								
2021	N	December	D								
2022	0										
2023	Р										
2024	R										
2025	S										
2026	Т										
2027	U										
2028	V										
2029	W										
2030	Х										

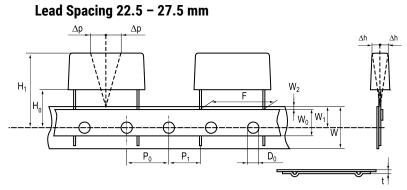


### **Packaging Quantities**

Lead Spacing	KEMET Size Code	Legacy Size Code	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Standard Reel ø 355 mm	Large Reel ø 500 mm	Ammo Bulk (Pizza)
	DD	D13	6.5	14.5	26.0	234	300	600	440
	DH	D14	8.0	16.0	26.0	186	250	500	352
	DM	D15	9.0	18.5	26.0	308	250	500	308
22.5	DT	D16	11.0	21.5	26.0	253	200	400	253
22.5	DF	D17	7.0	16.5	26.0	216	300	600	396
	DR	D18	10.5	19.0	26.0	264	200	400	264
	DY	D19	15.5	24.5	26.0	176	110	250	176
	DW	D20	13.5	23.0	26.0	209	160	300	209
	51/	500	10 5	00.0	01 5	171		050	171
	FK	F03	13.5	23.0	31.5	171		250	171
	FE	F11	10.5	20.5	31.5	216		350	216
	FG	F12	11.5	22.5	31.5	198		300	198
	FM	F13	14.5	24.5	31.5	153		250	153
27.5	FR	F14	17.5	28.0	31.5	126			126
	FS	F15	19.0	29.0	31.5	117			117
	FV	F16	21.0	30.0	31.5	108			108
	FH	F17	21.0	12.5	31.5	108			108
	FT	F18	31.0	18.5	31.5	72			72
	FQ	F19	27.5	16.0	31.5	81			81
	RK	R02	16.5	32.0	41.0	105			105
	RM	R02	19.0	36.0	41.0	91			91
	RH	R04	15.0	26.0	41.0	119			119
37.5	RF	R05	13.0	24.0	41.0	140			140
	RP	R06	21.0	38.0	41.0	84			84
	RS	R08	28.0	43.0	41.0	54			54



#### Lead Taping & Packaging (IEC 60286-2)



#### **Taping Specification**

		D	)imensions (mn	ו)
Description	Symbol	ymbol Lead Space		
		22.5	27.5	Tolerance
Lead Spacing	F	22.5	27.5	+0.6/-0.1
Carrier Tape Width	W	18	18	+1/-0.5
Hold Down Tape Width	W <sub>o</sub>	5	5	Minimum
Hole Position	W <sub>1</sub>	9	9	+0.75/-0.5
Hold Down Tape Position	W <sub>2</sub>	3	3	Maximum
Feed Hole Diameter	D <sub>0</sub>	4	4	±0.2
Feed-hole Lead Space *	P <sub>0</sub>	12.7	12.7	±0.2 **
Centering of the Lead Wire	P <sub>1</sub>	7.8	5.3	±0.7
Component Alignment	Δh	2	2	±2
Deviation Tape – Plane	Δp	1.3	1.3	Maximum
Tape Thickness	t	0.9	0.9	Maximum
Height of Component from Tape Center	H <sub>0</sub> ***	18.5	18.5	±0.5

\*Available also 15mm

\*\*Maximum 1 mm on 20 lead spaces

\*\*\* H<sub>0</sub> = 16.5 mm is available upon request



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PHE845VW7100MR06L	2 PHE845VR6470MR06L	2 PHE845VR6680MR06L	.2 PHE845VD5100MR06L2
PHE845VD5150MR06L2	PHE845VD5220MR06L2	PHE845VD5330MR06L2	PHE845VD5470MR06L2
PHE845VD5680MR06L2	PHE845VD6100MR06L2	PHE845VD6150MR06L2	PHE845VF6100MR06L2
PHE845VF6150MR06L2	PHE845VF6330MR06L2	PHE845VY6220MR06L2	PHE845VZ6470MR06L2
PHE845VF6220MR17L2	PHE845VF6220MR06L2	PHE845VF6100MR30L2	PHE845VW7100MR30L2
PHE845VZ6470MR30L2	PHE845VF6220MR30L2	PHE845VD5220MR30L2	PHE845VY6220MR30L2
PHE845VD5100MR30L2	PHE845VD5470MR30L2	PHE845VD6100MR30L2	PHE845VD5470MR30LL2
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